



Material Content Data Sheet



Sales Product Name				IPG16N10S4L-61A		Issued		4. July 2019	
MA#				MA004999452					
Package				PG-TDSON-8-10		Weight*		98.78 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	0.692	0.70	0.70	7005	7005	
chip_2	inorganic material	silicon	7440-21-3	0.692	0.70	0.70	7005	7005	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		133		
	non noble metal	iron	7439-89-6	0.044	0.04		443		
wire	non noble metal	copper	7440-50-8	43.681	44.25	44.30	442220	442796	
	non noble metal	aluminium	7429-90-5	0.790	0.80	0.80	7999	7999	
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		936		
	plastics	epoxy resin	-	6.562	6.64		66427		
leadfinish	inorganic material	silicondioxide	60676-86-0	39.554	40.04	46.77	400434	467797	
	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14137	14137	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15		
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6105	6120	
solder	non noble metal	tin	7440-31-5	0.039	0.04		396		
	noble metal	silver	7440-22-4	0.049	0.05		495		
heatspreader	non noble metal	lead	7439-92-1	1.866	1.89	1.98	18893	19784	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		8		
*deviation	non noble metal	iron	7439-89-6	0.003	0.00		27		
	non noble metal	copper	7440-50-8	2.699	2.73	2.73	27322	27357	
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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